

GSM6320TF

60V N-Channel MOSFET

Product Description

The N-Channel enhancement mode power field effect transistor is using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode.

The device is well suited for high efficiency fast switching applications.

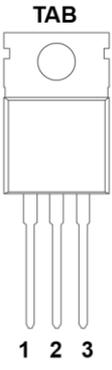
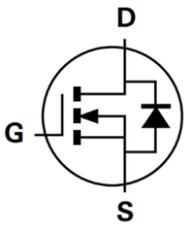
Features

- $R_{DS(ON)} = 2.8m\Omega @ V_{GS}=10V$
- $R_{DS(ON)} = 4m\Omega @ V_{GS}=4.5V$
- TO-220-3L Package
- RoHS Compliant and Halogen Free

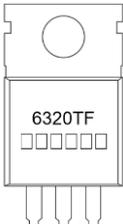
Applications

- MB / VGA / Vcore
- POL Applications
- SMPS

Packages & Pin Assignments

| TO-220-3L | | | Equivalent Circuit | | |
|---|--------|-------------|---|--------|-------------|
|  | | |  | | |
| Pin | Symbol | Description | Pin | Symbol | Description |
| 1 | G | Gate | 2 | D | Drain |
| 3 | S | Source | TAB | D | Drain |

Ordering and Marking Information

| Ordering Information | | | |
|--|-----------|--|-----------------|
| Part Number | Package | Part Marking | Quantity / Tube |
| GSM6320TF | TO-220-3L | 6320TF □□□□□□ | 50 PCS |
| GSM6320 1 2 | | | |
| - Product Code: GSM6320 | | - Package Code: 1 is T for TO-220-3L | |
| - Green Level: 2 is F for RoHS Compliant and Halogen Free | | | |
| Marking Information | | | |
|  | | - Product Code: 6320TF | |
| | | - GS Code: □□□□□□ | |

Absolute Maximum Ratings (T_A = 25°C unless otherwise specified)

| Symbol | Parameter | Value | Unit | |
|------------------|--|-----------------------|------|---|
| V _{DSS} | Drain-Source Voltage | 60 | V | |
| V _{GSS} | Gate-Source Voltage | ±20 | V | |
| I _D | Continuous Drain Current (Silicon Limited) | T _C =25°C | 178 | A |
| | | T _C =100°C | 112 | |
| | Continuous Drain Current (Package Limited) | | 120 | |
| I _{DM} | Pulsed Drain Current ¹ | 400 | A | |
| I _{AS} | Single Pulse Avalanche Current, L = 0.5mH ¹ | 25 | A | |
| E _{AS} | Single Pulse Avalanche Energy, L = 0.5mH ¹ | 312 | mJ | |
| P _D | Power Dissipation | T _C =25°C | 178 | W |
| | | T _C =100°C | 71 | |
| R _{θJC} | Thermal Resistance-Junction to Case | 0.7 | °C/W | |
| R _{θJA} | Thermal Resistance-Junction to Ambient ² | 62 | °C/W | |
| T _J | Operating Junction Temperature Range | -55 to +150 | °C | |
| T _{STG} | Storage Temperature Range | -55 to +150 | °C | |

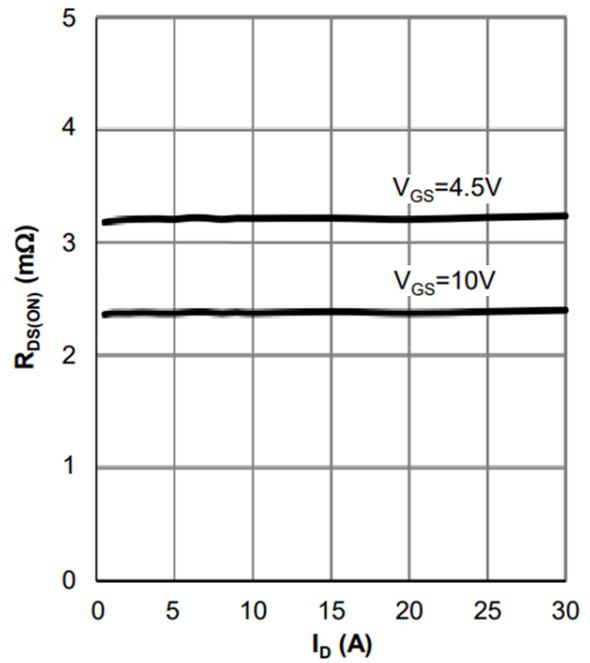
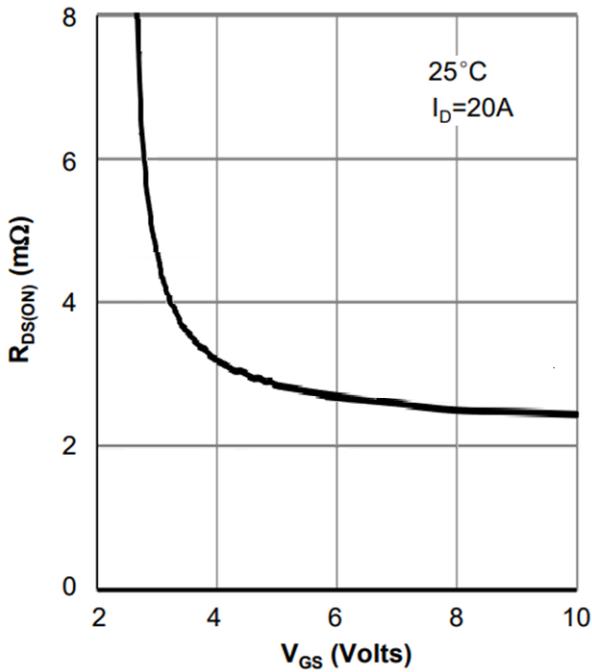
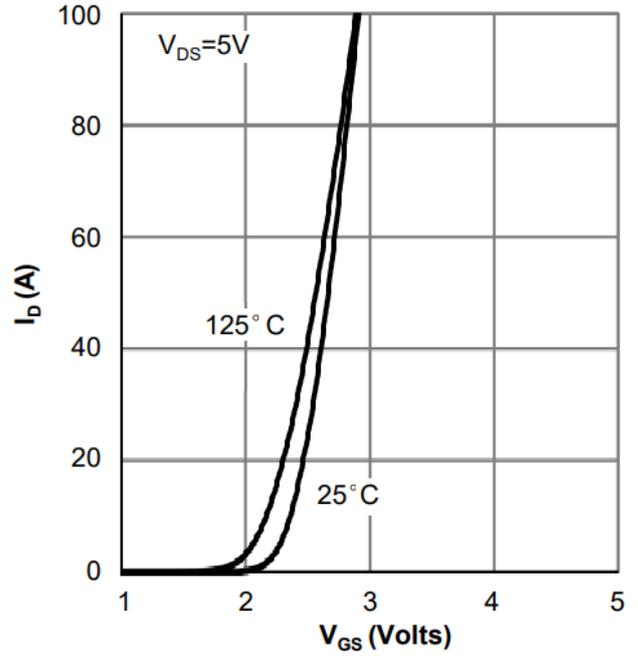
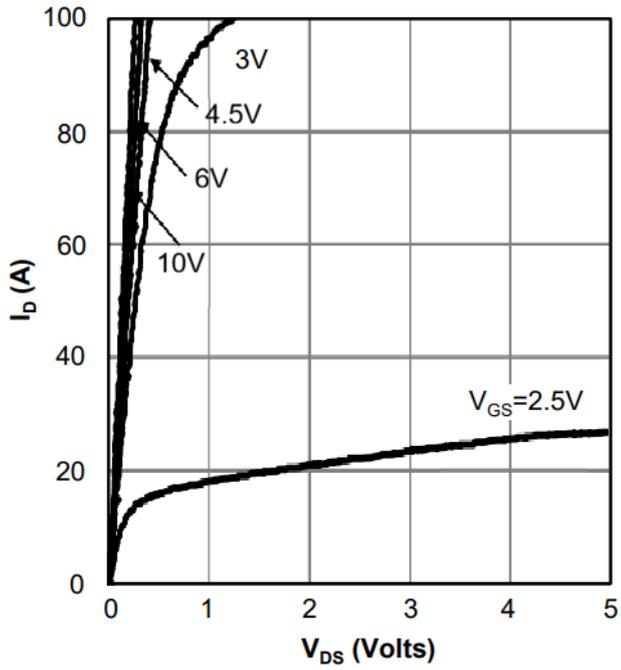
NOTE:

- Single pulse width is limited by max junction temperature.
- The device mounted on 1in² FR-4 board with 2oz. Copper

Electrical Characteristics (T_J = 25°C unless otherwise specified)

| Symbol | Parameter | Test Conditions | Min. | Typ. | Max. | Unit |
|--------------------------------|--------------------------------|---|------|------|------|------|
| Static Characteristics | | | | | | |
| B _V DSS | Drain-Source Breakdown Voltage | V _{GS} =0V, I _D =250μA | 60 | - | - | V |
| I _{DSS} | Drain-Source Leakage Current | V _{DS} =60V, V _{GS} =0V | - | - | 1 | μA |
| I _{GSS} | Gate-Source Leakage Current | V _{DS} =0V, V _{GS} =±20V | - | - | ±100 | nA |
| V _{GS(th)} | Gate Threshold Voltage | V _{DS} =V _{GS} , I _D =250μA | 1.2 | - | 2.5 | V |
| R _{DS(ON)} | Drain-Source On-Resistance | V _{GS} =10V, I _D =20A | - | 2.4 | 2.8 | mΩ |
| | | V _{GS} =4.5V, I _D =10A | - | 3.2 | 4 | |
| g _{fs} | Forward Transconductance | V _{DS} =5V, I _D =20A | - | 54 | - | S |
| Dynamic Characteristics | | | | | | |
| R _g | Gate Resistance | f=1MHz | | 1.8 | | Ω |
| C _{iss} | Input Capacitance | V _{DS} =30V, V _{GS} =0V, f=1MHz | - | 4947 | - | pF |
| C _{oss} | Output Capacitance | | - | 2850 | - | |
| C _{rss} | Reverse Transfer Capacitance | | - | 26 | - | |
| Q _g | Total Gate Charge | V _{DS} =30V, I _D =50A V _{GS} =10V | - | 98 | - | nC |
| Q _{gs} | Gate-Source Charge | | - | 18 | - | |
| Q _{gd} | Gate-Drain Charge | | - | 24 | - | |
| t _{d(on)} | Turn-On Delay Time | V _{DD} =30V, I _D =50A V _{GS} =10V, R _g =6Ω | - | 25 | - | ns |
| t _r | Turn-On Rise Time | | - | 45 | - | |
| t _{d(off)} | Turn-Off Delay Time | | - | 53 | - | |
| t _f | Turn-Off Fall Time | | - | 34 | - | |
| Diode Characteristics | | | | | | |
| V _{SD} | Diode Forward Voltage | V _{GS} =0V, I _S =1A | - | - | 1 | V |
| t _{rr} | Reverse Recovery Time | I _F =10A, dI/dt=100A/μs | - | 52 | - | ns |
| Q _{rr} | Reverse Recovery Charge | | - | 90 | - | nC |

Typical Performance Characteristics



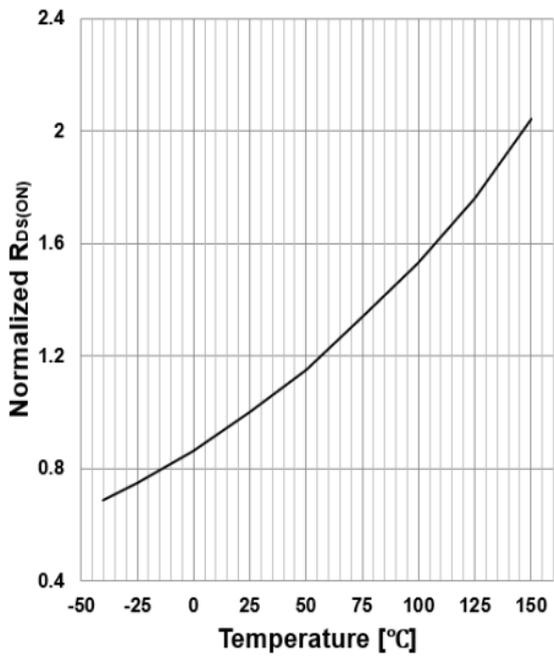


FIG.5 Normalized On-Resistance vs. T_J

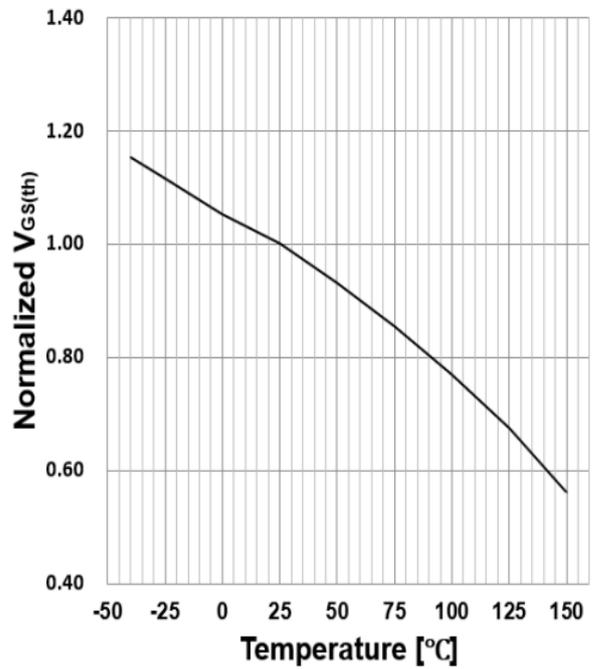


FIG.6 Normalized $V_{GS(th)}$ vs. T_J

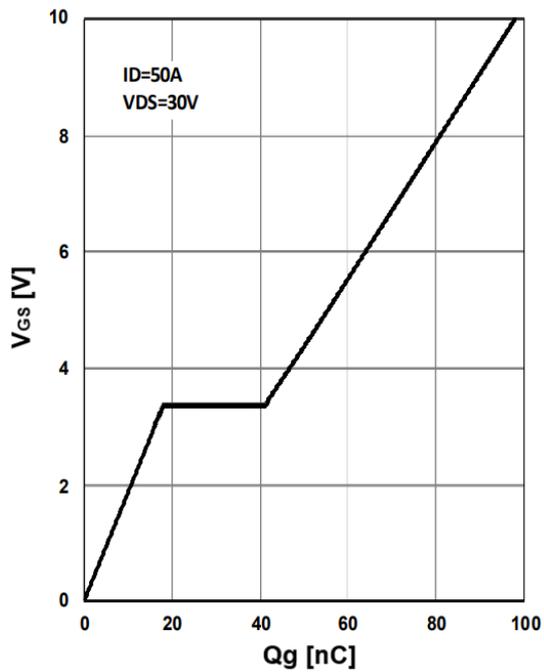


FIG.7 Gate Charge Characteristics

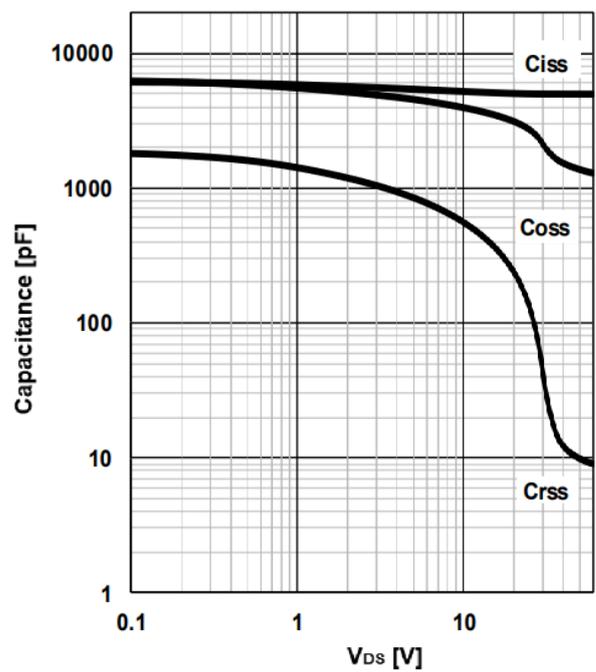


FIG.8 Capacitance Characteristics

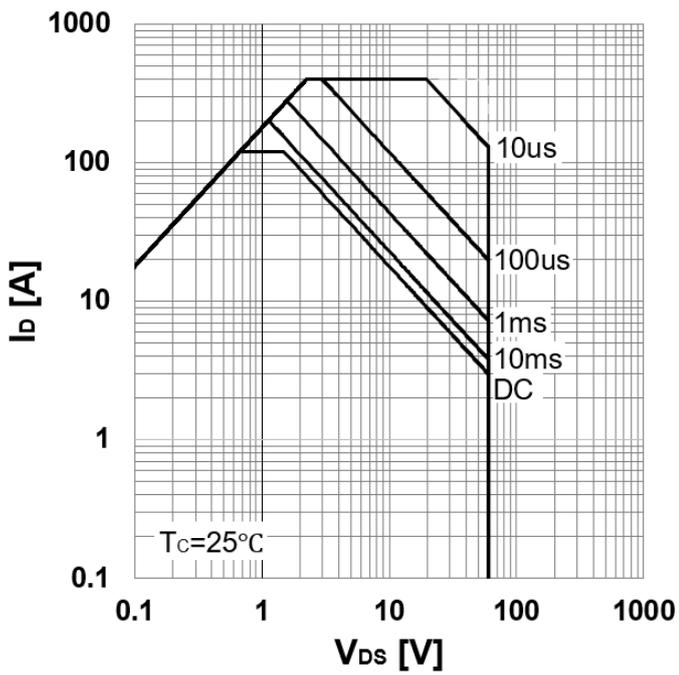


FIG.9 Maximum Safe Operation Area

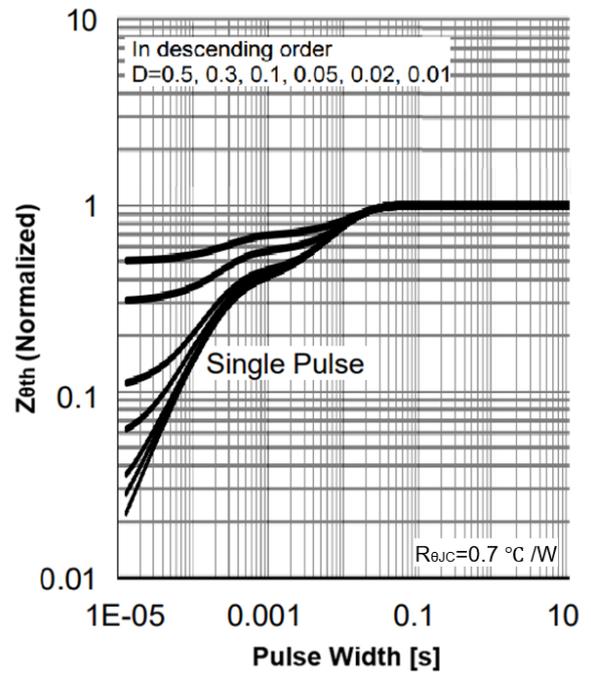


FIG.10 Transient Thermal Impedance (Normalized)

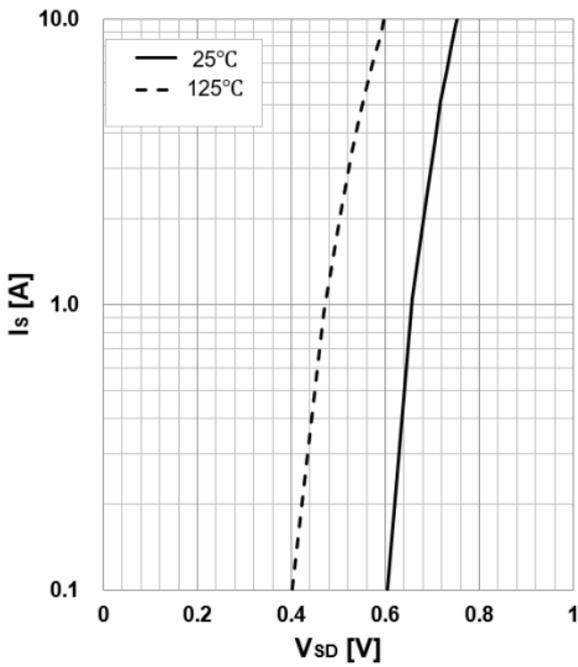
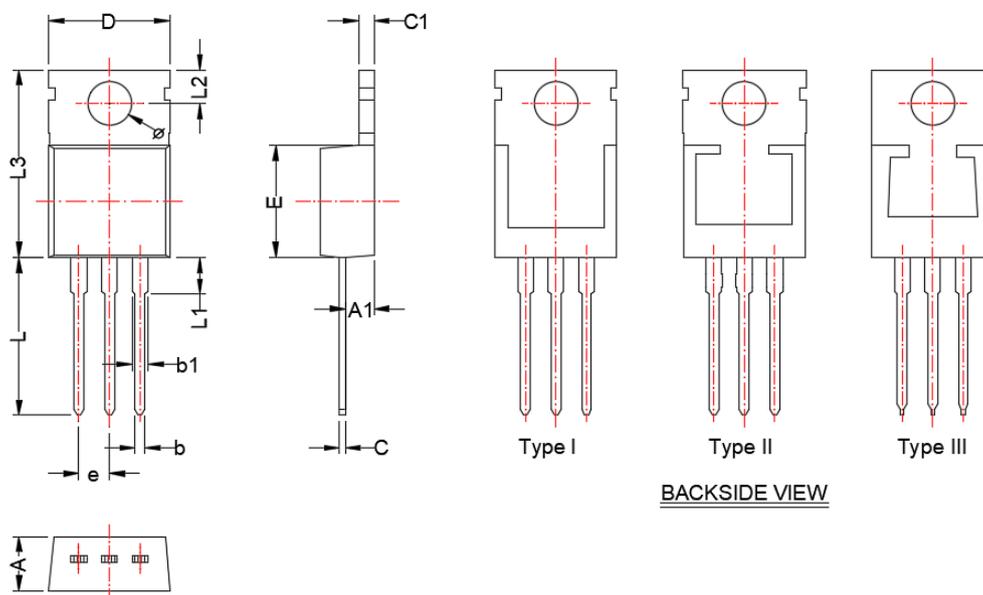


FIG.11 Body-Diode Characteristics

TO-220-3L

Package Dimension



| Dimensions | | | | |
|------------|-------------|-------|-----------|-------|
| Symbol | Millimeters | | Inches | |
| | Min | Max | Min | Max |
| A | 3.56 | 4.82 | 0.140 | 0.190 |
| A1 | 2.03 | 2.92 | 0.080 | 0.115 |
| b | 0.38 | 1.14 | 0.015 | 0.045 |
| b1 | 1.00 | 1.78 | 0.039 | 0.070 |
| c | 0.30 | 1.14 | 0.012 | 0.045 |
| c1 | 0.51 | 1.50 | 0.020 | 0.059 |
| D | 9.50 | 10.67 | 0.374 | 0.420 |
| E | 8.38 | 9.42 | 0.330 | 0.371 |
| e | 2.54 BSC | | 0.100 BSC | |
| L | 12.00 | 14.73 | 0.472 | 0.250 |
| L1 | --- | 7.00 | --- | 0.250 |
| L2 | 2.54 | 3.43 | 0.100 | 0.135 |
| L3 | 14.22 | 16.51 | 0.560 | 0.650 |
| ø | 3.40 | 4.09 | 0.134 | 0.161 |

NOTE:
Dimensions are exclusive of Burrs, Mold Flash and Tie Bar extrusions.

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